Product Specification

Product:	**Dielectric Paste**
Part Number:	**07MT-FD46**

Application Scope :

The paste is suitable for thick film circuit filling and device bonding, and can be used on ceramic, glass, metal and other substrates.

Usage Conditions :

Substrate	Thick-film circuit, alumina ceramic, ceramic, glass, metal
Usage Method	Lattice printing
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (the baking temperature should not exceed 300°C, and the baking time may be adjusted based on actual conditions).
Firing Condition	The sintering temperature is 450±10°C (recommended value, the minimum 400°C can be vitrified) and the sintering time is 10~30 minutes. The sintering range can be adjusted within 390-580°C as needed, but the peak temperature duration must exceed 10 minutes. If the sintering temperature is too low, the peak time should be appropriately extended until complete vitrification is achieved, typically recommended for approximately 30 minutes.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤8μm	FOG test
2	Viscosity	350~500Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R), 10 rpm, 25±1°C
3	Appearance	**Achromatic colour, Transparent**	

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1）

Characteristics		Standard	Test Method And Conditions
4	Appearance	Compact and dense	Visual inspection & microscopy

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.